

ABOUT ASMPT OUR VISION: ENABLING THE DIGITAL WORLD

ASMPT, founded in 1975, is the only company in the world that offers high-quality equipment for all major steps in the electronics manufacturing process from carrier for chip interconnection to chip assembly and packaging to SMT. No other supplier offers a comparable range and depth of process expertise.

Our Semiconductor Solutions Segment Business offers a diverse product range from bonding to molding and trim & form to the integration of these activities into complete in-line systems for the microelectronics, semiconductor, photonics, and optoelectronics industries. Our Materials Business provides customers with a variety of leadframes such as etched and stamping as well as advanced packaging materials. Our SMT Solutions develops and sells best-in-class DEK printers for the SMT, semiconductor and solar markets as well as best-in-class SIPLACE SMT placement solutions.

ASMPT is headquartered in Singapore and is listed in Hong Kong Stock Exchange since 1989

ASMPT AT A GLANCE

>14,000 **Employees** Worlwide

>2000 Global R&D Staff

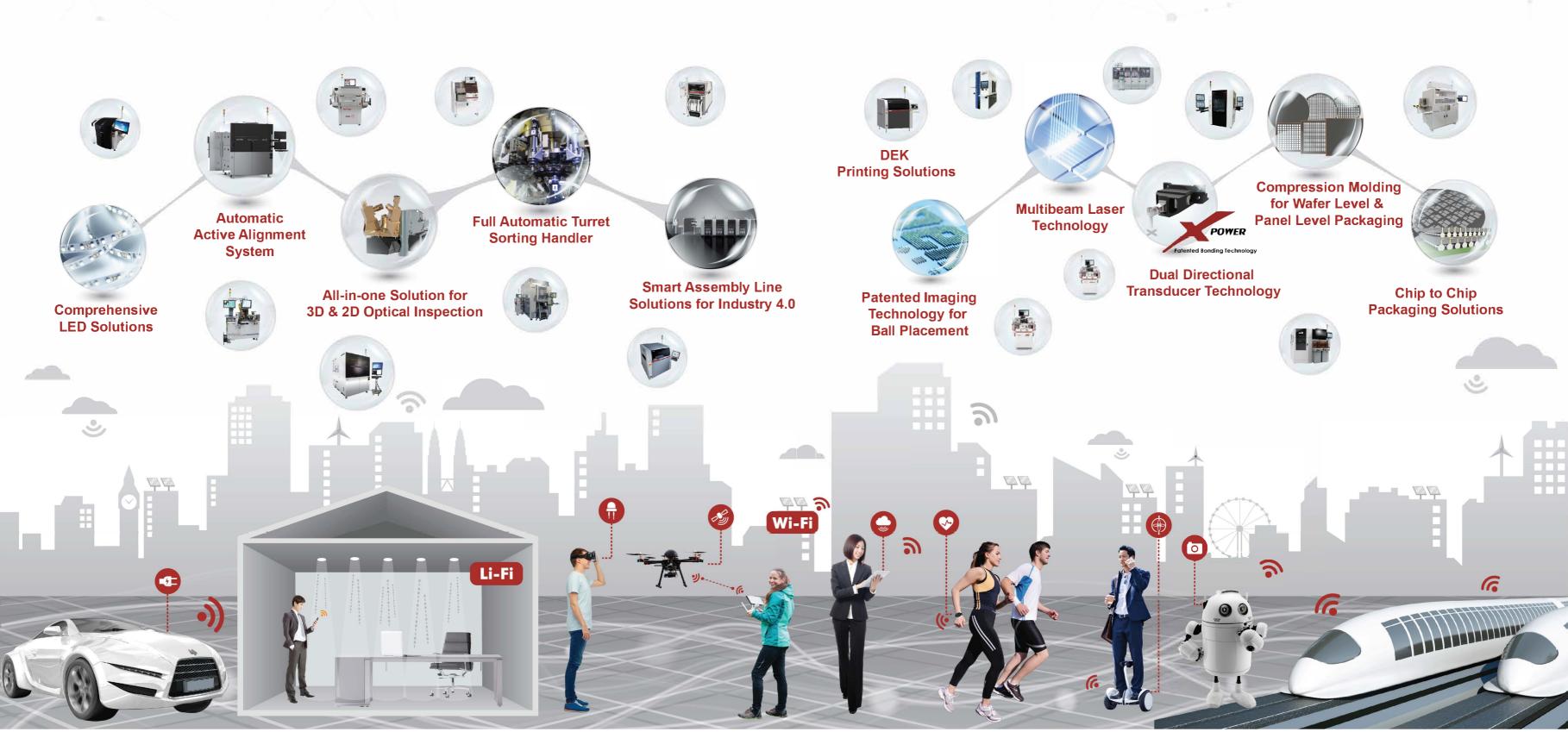
>1,400

Patents on key leading edge technologies

30+

Present in Countries **R&D** Centres Worldwide

Significant Manufacturing **Operations Worldwide**



THE INTEGRATED SOLUTIONS COMPANY



Hardware

Semiconductor Solutions Segment

- Laser Grooving & Dicing
- Wire Bonders & Die Bonders
- Encapsulation Solutions, Test Handlers, Clip Bonders, CIS Equipment
- TCB Bonders, Flip Chip Bonders, Mold Under Fill (MUF), Panel Molding
- Wafer Level Sputtering Equipment
- Wafer Level Plating Equipment



SMT Solutions

- Assembly line solutions
- DEK printing systems
- SIPLACE placement systems





Software

Industry 4.0 Solutions

- ASM smart factory tools and services
- Manufacturing Execution Software (Critical Manufacturing & SKT)

